**TOSHIBA** 2SJ407

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE ( $\pi$ -MOS V)

# 2 S J 4 0 7

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 0.8\Omega$  (Typ.)

High Forward Transfer Admittance : |Yfs|=4.0S (Typ.)

Low Leakage Current :  $I_{DSS} = -100 \mu A$  (Max.) ( $V_{DS} = -200 V$ )

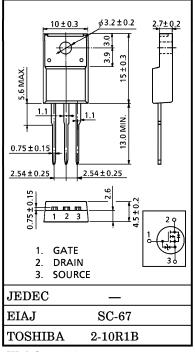
Enhancement-Mode  $: V_{th} = -1.5 \sim -3.5 V$ 

 $(V_{DS} = -10V, I_D = -1mA)$ 

### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Volta	$V_{ m DSS}$	-200	V	
Drain-Gate Voltage (R <sub>GS</sub> =20kΩ)		$v_{ m DGR}$	-200	V
Gate-Source Voltag	$V_{GSS}$	±20	V	
Drain Current	DC	$I_{\mathbf{D}}$	-5	A
	Pulse	$I_{\mathrm{DP}}$	-20	A
Drain Power Dissip	$P_{\mathbf{D}}$	30	W	
Single Pulse Avalanche Energy**		EAS	195	mJ
Avalanche Current		$I_{AR}$	-5	A
Repetitive Avalanche Energy*		$\mathrm{E}_{\mathrm{AR}}$	3.0	mJ
Chanel Temperatur	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Range		$T_{ m stg}$	-55~150	°C

# INDUSTRIAL APPLICATIONS Unit in mm



Weight: 1.9g

# THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Chanel To Case	R <sub>th (ch-c)</sub>	4.16	°C/W
Thermal Resistance, Chanel to Ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

#### Note;

- Repetitive rating; Pulse Width Limited by Max. junction
- \*\*  $V_{DD} = -50V$ , Starting  $T_{ch} = 25$ °C, L = 12.6mH,  $R_G = 25\Omega$ ,  $I_{AR} = -5A$

This transistor is an electrostatic sensitive device. Please handle with caution.

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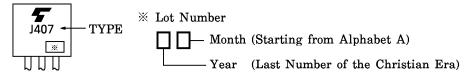
# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACT	ERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT		
Gate Leakage C	Gate Leakage Current		$V_{GS} = \pm 16V, V_{DS} = 0V$	_	_	±10	$\mu$ A		
Drain Cut-off C	urrent	$I_{ m DSS}$	$V_{DS} = -200V, V_{GS} = 0V$	_	_	-100	$\mu$ A		
Drain-Source Br	eakdown	V <sub>(BR)</sub>	$I_D = -10$ mA, $V_{GS} = 0$ V	-200			v		
Voltage		DSS	ID = IOMA, VGS = 0V		_	_	v		
Gate Threshold	Voltage	$ m v_{th}$	$V_{DS} = -10V, I_D = -1mA$	-1.5	_	-3.5	V		
Drain-Source O	N Resistance	R <sub>DS</sub> (ON)	$V_{GS} = -10V, I_D = -2.5A$	_	0.8	1.0	Ω		
Forward Transfe	er Admittance	Yfs	$V_{DS} = -10V, I_D = -2.5A$	2.0	4.0	_	S		
Input Capacitance		$\mathrm{c_{iss}}$	Vpg 10V Vgg 10V	1	800	_	pF		
Reverse Transfer Capacitance		$\mathrm{C}_{\mathrm{rss}}$	$V_{ m DS}\!=\!-10{ m V,}\ V_{ m GS}\!=\!0{ m V} \ -{ m f}\!=\!1{ m MHz}$	_	80	_			
Output Capacitance		$C_{oss}$		_	270	_			
Switching Time	Rise Time	$t_r$	$V_{GS}$ $V_{GS}$ $V_{GS}$ $V_{OUT}$	_	15	_	ns		
	Turn-on Time	$t_{on}$			30				
	Fall Time	$t_f$		_	6	_			
	Turn-off Time	t <sub>off</sub>	$\begin{vmatrix} V_{\text{IN}} : t_{\text{r}}, t_{\text{f}} < 5\text{ns} & V_{\text{DD}} = -100V \\ \text{Duty} \le 1\%, t_{\text{W}} = 10\mu\text{s} \end{vmatrix}$	_	65	_			
Total Gate Charge									
(Gate-Source Plus Gate-		$\mathbf{Q}_{\mathbf{g}}$	V <sub>DD</sub> ≒ –160V	—	20	—			
Drain)			$V_{GS} = -10V$				nC		
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_D = -5A$	_	13	_			
Gate-Drain ("Miller") Charge		$ m Q_{gd}$		_	7	_			

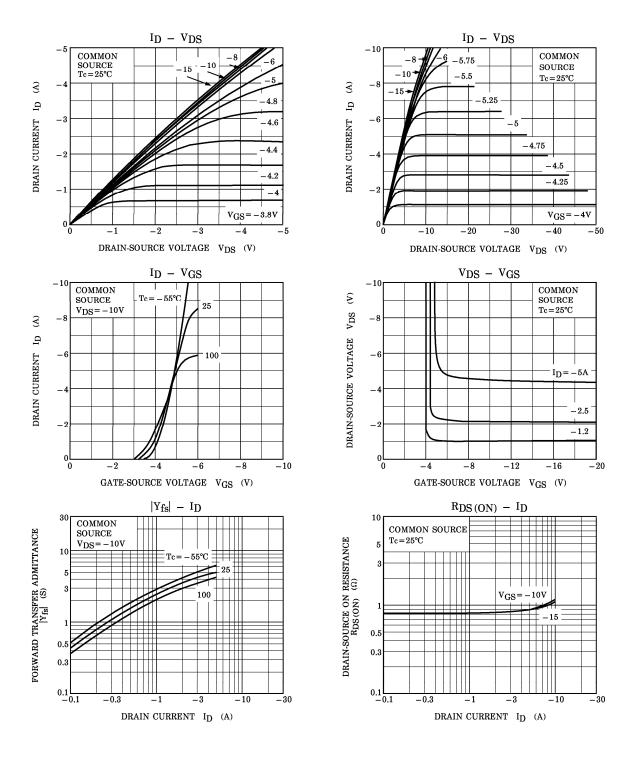
# SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

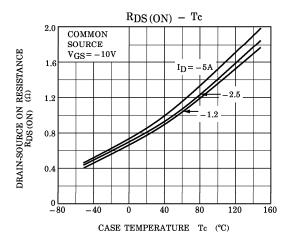
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	${ m I}_{ m DR}$	_	_	_	-5	Α
Pulse Drain Reverse Current	${ m I}_{ m DRP}$	_	_	_	-20	Α
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = -5A$ , $V_{GS} = 0V$	_	_	2.0	V
Reverse Recovery Time		$I_{DR} = -5A$ , $V_{GS} = 0V$	_	210	_	ns
Reverse Recovery Charge	$\mathrm{Q_{rr}}$	$dI_{ m DR}$ / $dt$ = 100A / $\mu s$	_	1.2	_	$\mu$ C

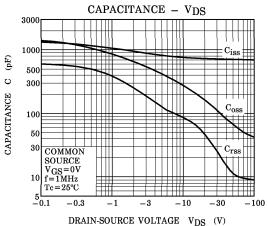
# MARKING

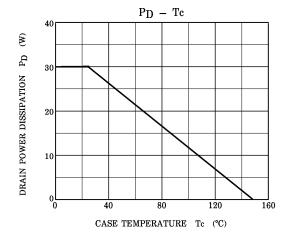


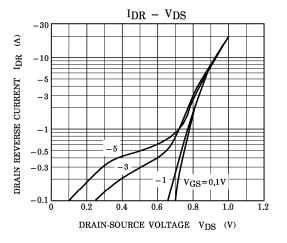
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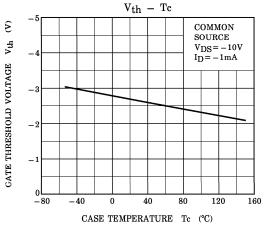


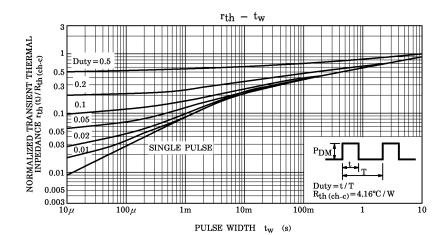


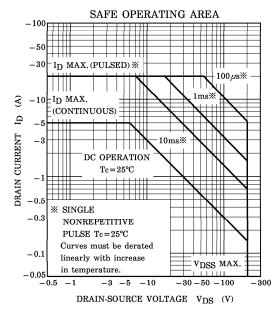


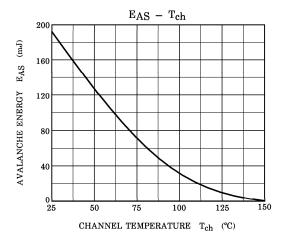


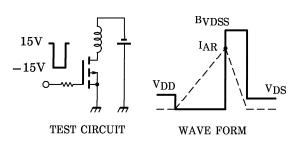












$$\begin{array}{ll} \text{Peak I}_{AR} = -5\text{A, R}_{G} = 25\Omega \\ \text{V}_{DD} = -50\text{V, L} = 12.6\text{mH} \end{array} \quad \text{E}_{AS} = \frac{1}{2} \cdot \text{L} \cdot \text{I}^{2} \cdot (\frac{\text{BVDSS}}{\text{BVDSS} - \text{V}_{DD}}) \end{array}$$